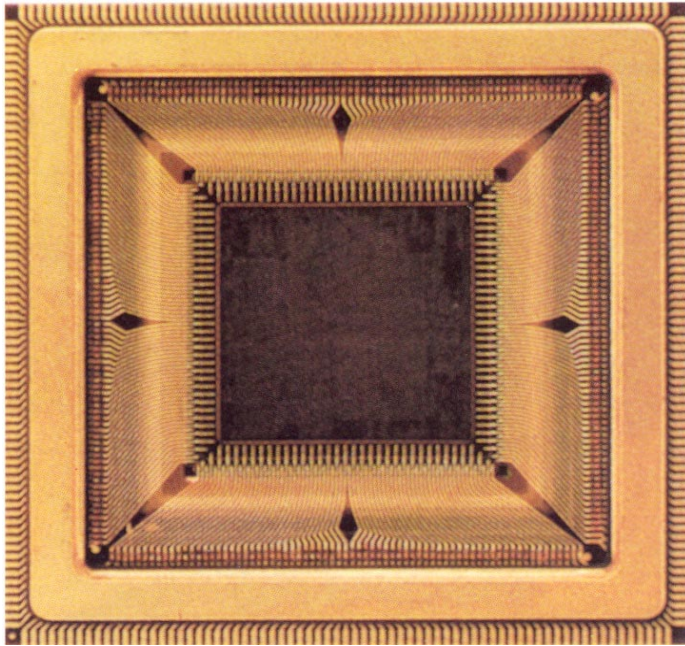




# Kapton®

polyimide film

## Kapton® Type E Film for Tape Automated Bonding Applications and Flexible Printed Circuits



### Typical Properties of Kapton® Type E Polyimide Film

Modulus	800 kpsi
Dim. properties	CTE = 16 ppm/°C CHE = 9 ppm/% RH shrinkage = 0.03% (200°C)
Low water absorption	2.2%
Easily etchable	common caustic solutions
Higher productivity	better stiffness for stability during processing

### Kapton® Type E

#### Features:

- E polymer formulation
- Substrate film for either 2-layer (metallized) or 3-layer (adhesive coated) TAB
- High modulus
- Tailored dimensional properties (thermal expansion matched to copper)
- Easily etchable
- Laser ablatable
- Fast drying rate
- Fast adhesive cure rate
- Low absorption and less expansion in water
- High/durable adhesion (85°C/85% RH)

#### Available:

- 100TAB-E
- 200TAB-E

Other gauges may be available upon request.

#### Applications:

- TBGA Substrate
- Disk drive circuits
- TAB type circuits

United States (800) 967-5607 – Canada (800) 784-5231 – Europe 352-3666-4004  
 Japan 81-3-5434-6139 - DuPont Toray Co. 81-3-3245-5061 – Hong Kong 852-2734-5461  
 China/Beijing 86-10-65227010 - India 91-22-8390770 – Korea 82-2-222-5399  
 Singapore 65-279-3527 - Taiwan 886-3-3773604